Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSIII)

2SK2611

DC-DC Converter, Relay Drive and Motor Drive Applications

• Low drain-source ON resistance $: RDS(ON) = 1.1 \Omega(typ.)$

• High forward transfer admittance $|Y_{fs}| = 7.0 \text{ S (typ.)}$

• Low leakage current : IDSS = $100 \mu A \text{ (max)} \text{ (VDS} = 720 \text{ V)}$

• Enhancement-mode $: V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	900	V	
Drain-gate voltage (Ro	_{SS} = 20 kΩ)	V_{DGR}	900	V	
Gate-source voltage		V_{GSS}	±30	V	
Drain current	DC (Note 1)	I _D	9	Α	
	Pulse (Note 1)	I _{DP}	27	Α	
Drain power dissipation	n (Tc = 25°C)	P_{D}	150	W	
Single pulse avalanche	e energy (Note 2)	E _{AS}	663	mJ	
Avalanche current		I _{AR}	9	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	15	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature ra	ange	T _{stg}	-55~150	°C	

Weight: 4.6 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	0.833	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	50	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 15 mH, R_G = 25 Ω , I_{AR} = 9 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device.

Please handle with caution.

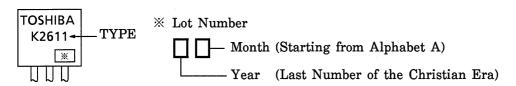
Electrical Characteristics (Ta = 25°C)

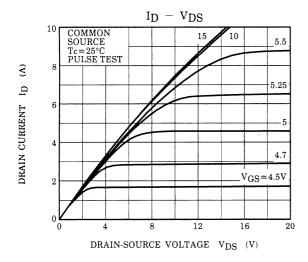
Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±30 V, V _{DS} = 0 V	_	_	±10	μΑ
Gate-source bro	eakdown voltage	V _(BR) GSS	$I_G = \pm 10 \mu\text{A}, V_{DS} = 0 \text{V}$	±30	_	_	V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 720 V, V _{GS} = 0 V	_	_	100	μΑ
Drain-source br	eakdown voltage	V _{(BR) DSS}	I _D = 10 mA, V _{GS} = 0 V	900	_	_	V
Gate threshold v	/oltage	V_{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 4 A	_	1.1	1.4	Ω
Forward transfe	r admittance	Y _{fs}	V _{DS} = 15 V, I _D = 4 A	3.0	7.0	_	S
Input capacitano	ce	C _{iss}		_	2040	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	_	45	_	pF
Output capacitance		Coss		_	190	_	
Switching time	Rise time	t _r	$V_{GS} \stackrel{10V}{\circ}_{OV} \stackrel{I_{D}=4A}{\longrightarrow}_{V_{DD}=400V} V_{out}$	_	25	_	
	Turn-on time	t _{on}		_	60	_	ne
	Fall time	t _f		_	20	_	ns
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_{W} = 10 \mu s$	_	95	_	
Total gate charge (gate-source plus gate-drain)		Qg		_	58	_	
Gate-source charge		Q _{gs}	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 9 \text{ A}$		32		nC
Gate-drain ("miller") Charge		Q_{gd}			26	_	

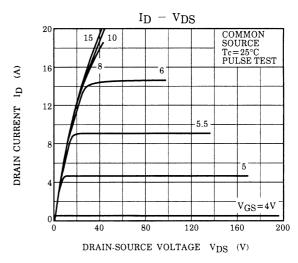
Source-Drain Ratings and Characteristics (Ta = 25°C)

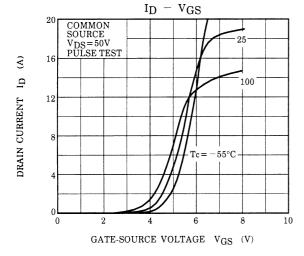
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	-	_	_	9	Α
Pulse drain reverse current (Note 1)	I _{DRP}	-	_	_	27	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 9 A, V _{GS} = 0 V	_	_	-1.9	V
Reverse recovery time	t _{rr}	I _{DR} = 9 A, V _{GS} = 0 V, dI _{DR} / dt = 100 A / μs	_	1.6		μs
Reverse recovery charge	Q _{rr}	1DK - 9 Λ, VGS - 0 V, αιDK / αι - 100 Α / μs	_	20	_	μC

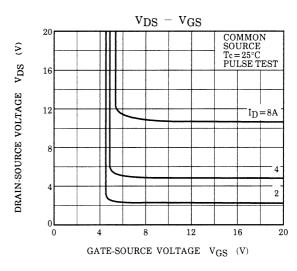
Marking

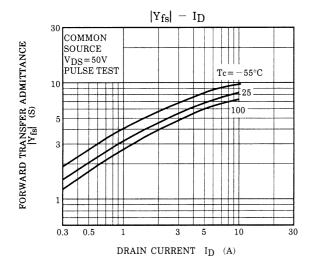


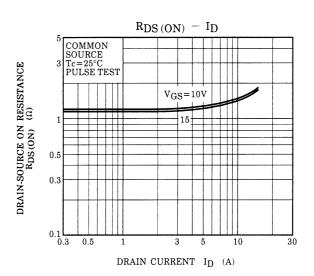


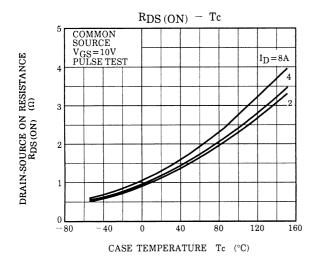


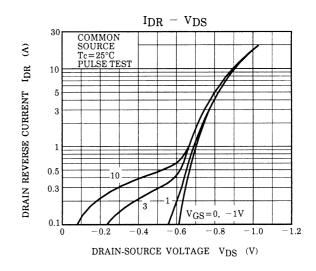


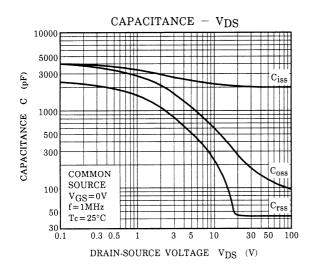


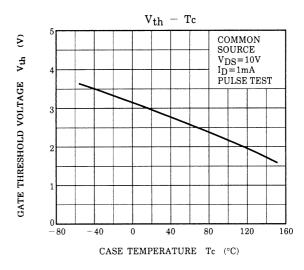


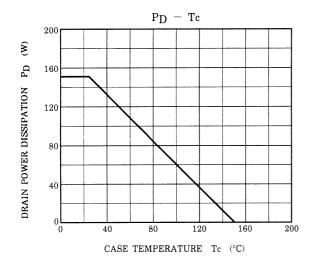


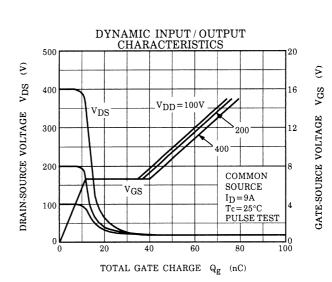




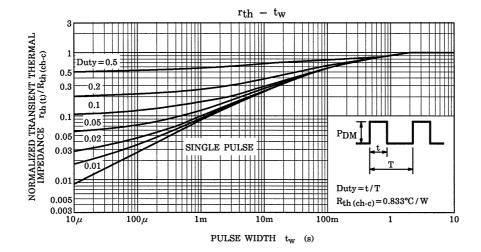


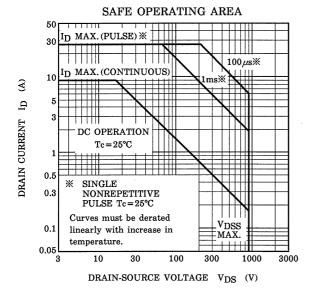


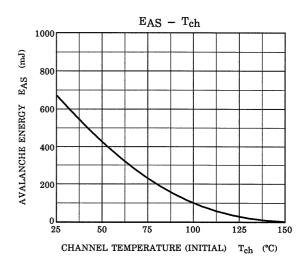


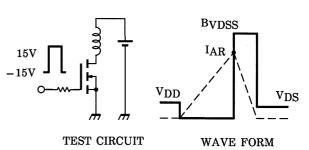


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$$R_G = 25 \Omega$$

 $V_{DD} = 90 \text{ V}, L = 15 \text{ mH}$ $E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}}\right)$

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